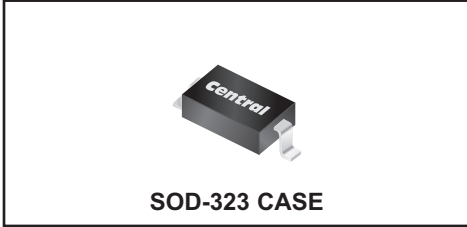


CMDSH2-3

**SURFACE MOUNT SILICON
HIGH CURRENT SCHOTTKY DIODE**



www.centrasemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMDSH2-3 is a silicon Schottky diode, manufactured in a SOD-323 surface mount package, designed for applications requiring a low forward voltage drop.

MARKING CODE: S2

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Peak Repetitive Reverse Voltage
 Continuous Forward Current
 Peak Forward Surge Current, $t_p=10\text{ms}$
 Power Dissipation
 Operating and Storage Junction Temperature
 Thermal Resistance

SYMBOL		UNITS
V_{RRM}	30	V
I_F	200	mA
I_{FSM}	1.0	A
P_D	250	mW
T_J, T_{stg}	-65 to +150	$^\circ\text{C}$
θ_{JA}	500	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$)

SYMBOL TEST CONDITIONS

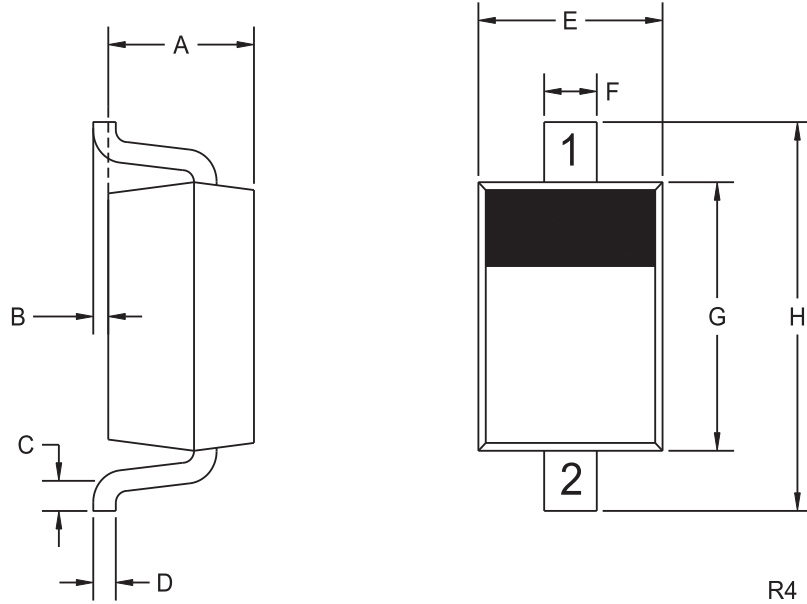
I_R $V_R=30\text{V}$
 BV_R $I_R=100\mu\text{A}$
 V_F $I_F=2.0\text{mA}$
 V_F $I_F=15\text{mA}$
 V_F $I_F=100\text{mA}$
 V_F $I_F=200\text{mA}$
 C_J $V_R=10\text{V}, f=1.0\text{MHz}$

MIN	TYP	MAX	UNITS
	19	50	μA
30			V
	0.186		V
	0.245		V
	0.35		V
	0.42	0.55	V
	6.0		pF

CMDSH2-3
SURFACE MOUNT SILICON
HIGH CURRENT SCHOTTKY DIODE



SOD-323 CASE - MECHANICAL OUTLINE



LEAD CODE:

- 1) Cathode
- 2) Anode

MARKING CODE: S2

SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.031	0.039	0.80	1.00
B	0.000	0.004	0.00	0.10
C	0.008	-	0.20	-
D	0.004	0.007	0.11	0.19
E	0.045	0.053	1.15	1.35
F	-	0.014	-	0.35
G	0.063	0.071	1.60	1.80
H	0.094	0.102	2.40	2.60

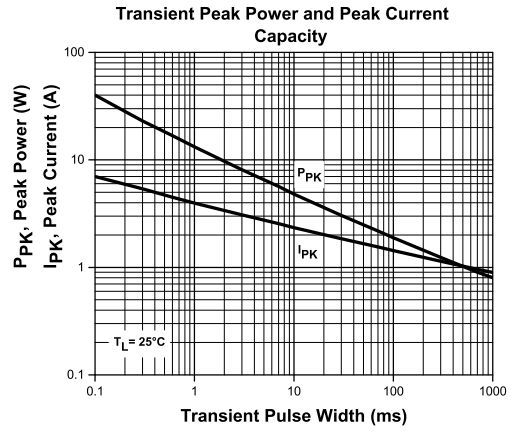
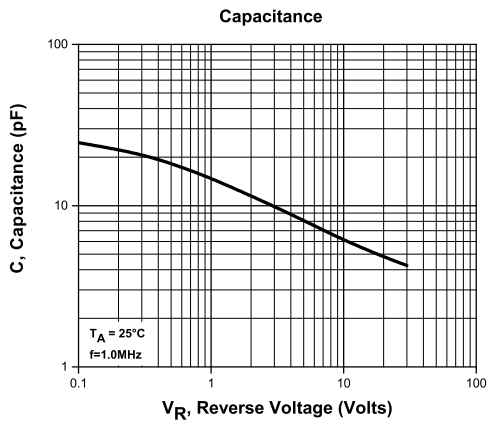
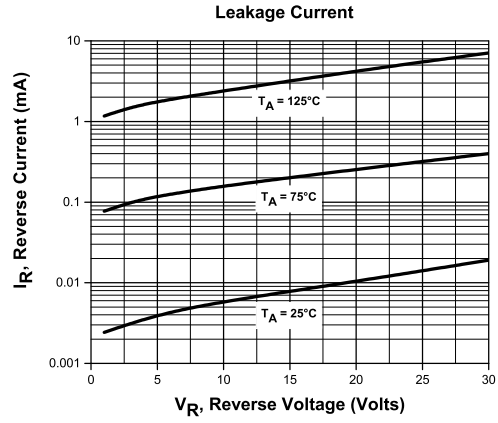
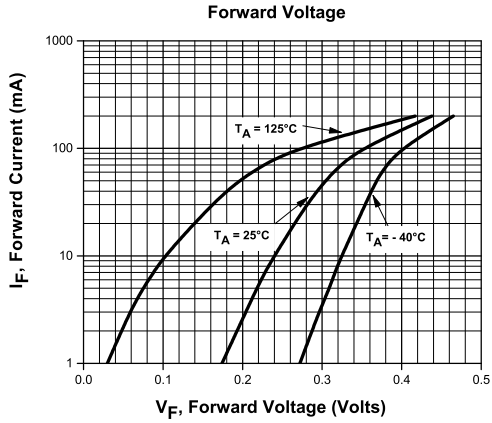
SOD-323 (REV: R4)

R4 (13-November 2015)

CMDSH2-3
SURFACE MOUNT SILICON
HIGH CURRENT SCHOTTKY DIODE



TYPICAL ELECTRICAL CHARACTERISTICS

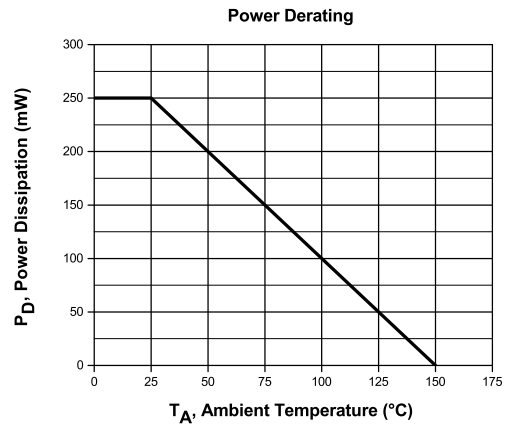
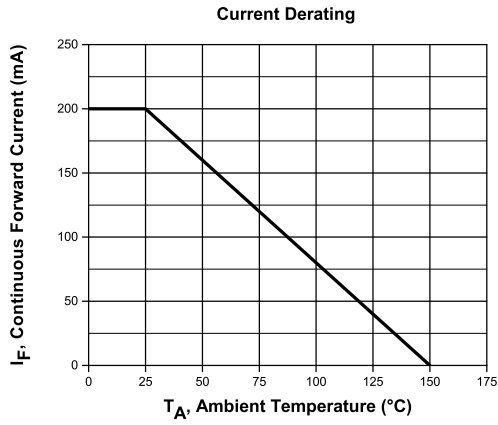


R4 (13-November 2015)

CMDSH2-3
SURFACE MOUNT SILICON
HIGH CURRENT SCHOTTKY DIODE



TYPICAL ELECTRICAL CHARACTERISTICS



R4 (13-November 2015)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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